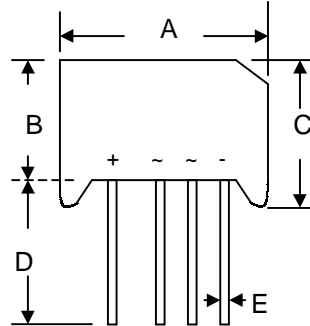
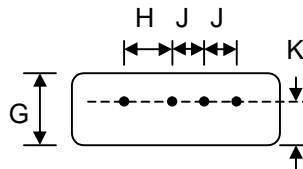


Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards



RS-5		
Dim	Min	Max
A	39.40	40.10
B	20.20	21.00
C	21.00	21.70
D	25.40	—
E	0.97 Ø	1.07 Ø
G	6.20	6.70
H	9.80	10.20
J	7.20	7.60
K	4.60	5.00
All Dimensions in mm		



Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 25.3 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	B40C3700/ 2200	B80C3700/ 2200	B125C3700/ 2200	B250C3700/ 2200	B380C3700/ 2200	Unit	
Peak Repetitive Reverse Voltage	V_{RRM}						V	
Working Peak Reverse Voltage	V_{RWM}	100	200	300	600	900	V	
DC Blocking Voltage	V_R						V	
Recommend Input Voltage	V_{RMS}	40	80	125	250	380	V	
Average Rectified Output Current @ $T_A = 45^\circ\text{C}$ (Note 1)	I_O	3.7						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100						A
Repetitive Peak Forward Surge Current	I_{FRM}	15						A
Forward Voltage (per element) @ $I_F = 3.0\text{A}$	V_{FM}	1.0						V
Peak Reverse Current @ $T_C = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_C = 150^\circ\text{C}$	I_R	10 6.0						μA mA
Rating for Fusing ($t < 8.3\text{ms}$) (Note 2)	I_t^2	50						A^2s
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	3.0						K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150						$^\circ\text{C}$

***Glass Passivated forms are available upon request.**

- Note: 1. Measured at 3"sq. x 0.11" thick AL. plate.
 2. Non-repetitive for $t > 1\text{ms}$ and $< 8.3\text{ms}$.

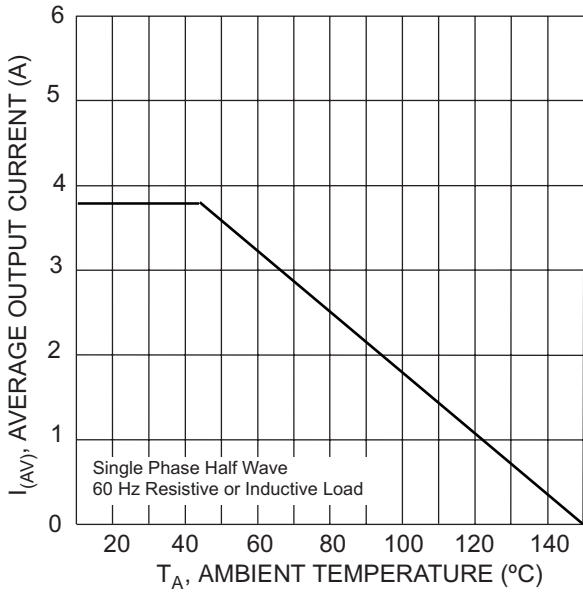


Fig. 1 Forward Current Derating Curve

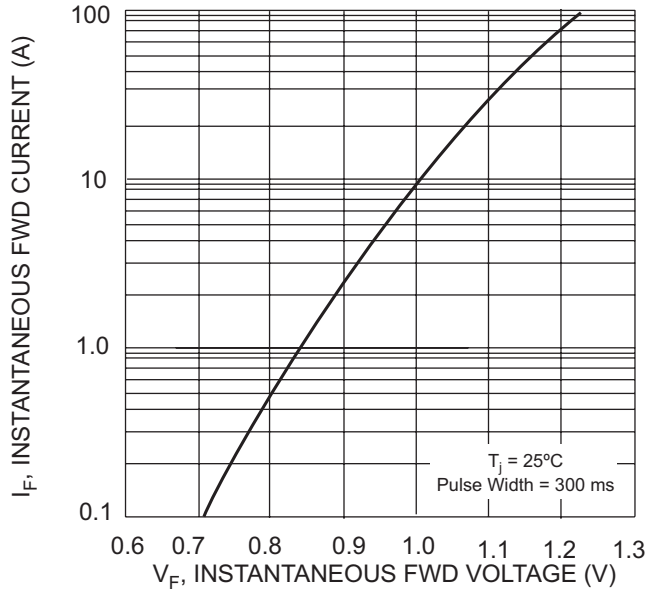


Fig. 2 Typical Forward Characteristics, per element

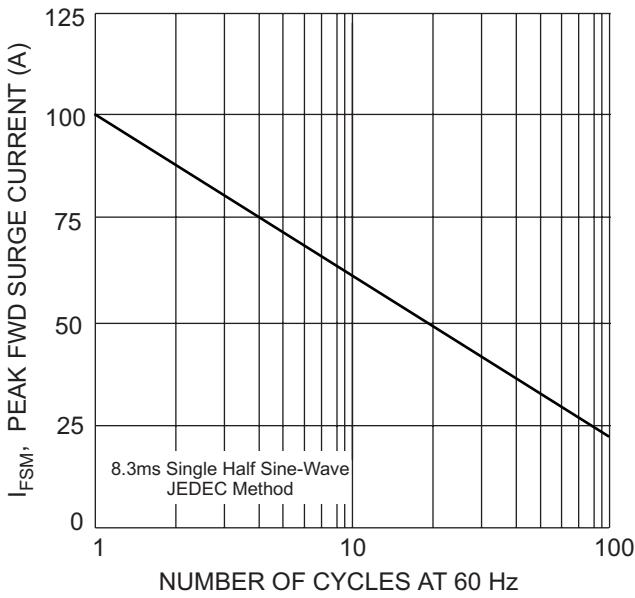


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

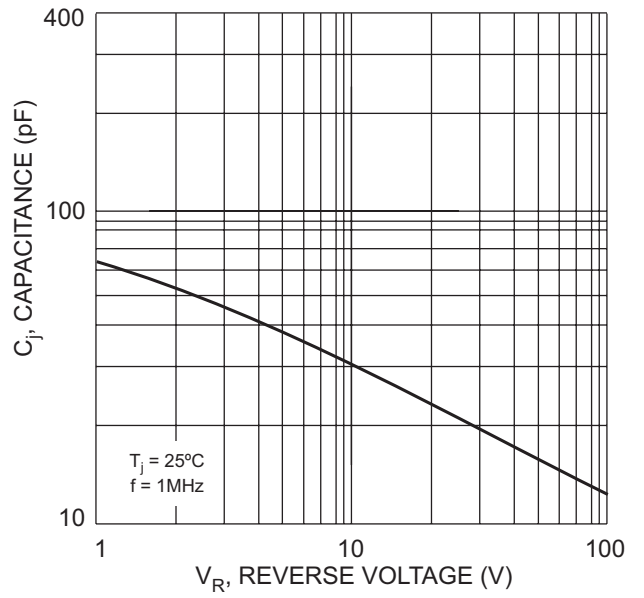


Fig. 4 Typical Junction Capacitance Per Element

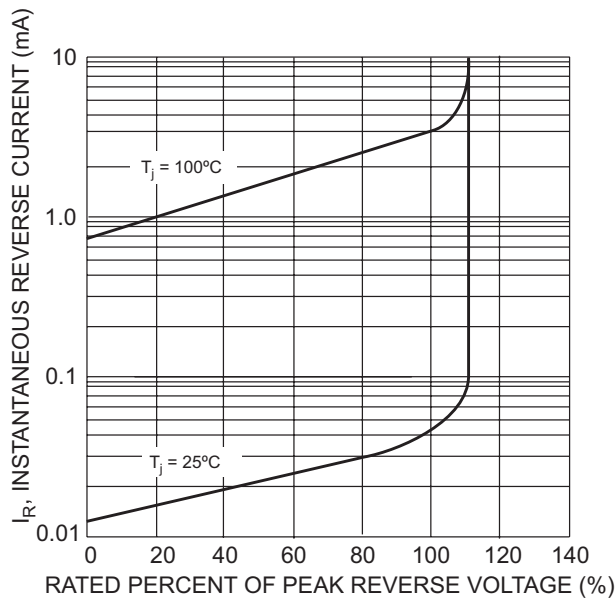


Fig. 5 Typical Reverse Characteristics

ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
B40C3700/2200	SIL Bridge	200 Units/Box
B80C3700/2200	SIL Bridge	200 Units/Box
B125C3700/2200	SIL Bridge	200 Units/Box
B250C3700/2200	SIL Bridge	200 Units/Box
B380C3700/2200	SIL Bridge	200 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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WARNING: DO NOT USE IN LIFE SUPPORT EQUIPMENT. WTE power semiconductor products are not authorized for use as critical components in life support devices or systems without the express written approval.

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